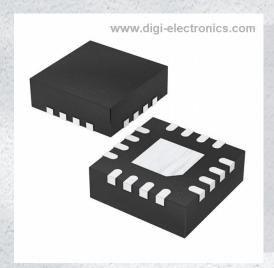


NB6L611MNG Datasheet



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DiGi Electronics Part Number NB6L611MNG-DG

Manufacturer onsemi

Manufacturer Product Number NB6L611MNG

Description IC CLK BUFFER 1:2 4GHZ 16QFN

Detailed Description Clock Fanout Buffer (Distribution) IC 1:2 4 GHz 16-V

FQFN Exposed Pad



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



Purchase and inquiry

Manufacturer Product Number:	Manufacturer:
NB6L611MNG	onsemi
Series:	Product Status:
ECLinPS MAX™	Active
Type:	Number of Circuits:
Fanout Buffer (Distribution)	1
Ratio - Input:Output:	Differential - Input:Output:
1:2	Yes/Yes
Input:	Output:
CML, LVCMOS, LVDS, LVPECL, LVTTL	LVPECL
Frequency - Max:	Voltage - Supply:
4 GHz	2.375V ~ 3.63V
Operating Temperature:	Mounting Type:
-40°C ~ 85°C	Surface Mount
Package / Case:	Supplier Device Package:
16-VFQFN Exposed Pad	16-QFN (3x3)
Base Product Number:	
NB6L611	

Environmental & Export classification

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	1 (Unlimited)
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	
8542.39.0001	

1



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2.5 V / 3.3 V 1:2 Differential LVPECL Clock / Data Fanout Buffer

Multi-Level Inputs with Internal Termination

NB6L611

Description

The NB6L611 is a differential 1:2 clock or data fanout buffer. The differential inputs incorporate internal 50 Ω termination resistors that are accessed through the VTD pins and will accept LVPECL, CML, LVDS, LVCMOS or LVTTL logic levels.

The V_{REFAC} reference output can be used to rebias capacitor–coupled differential or single–ended input signals. When used, decouple V_{REFAC} with a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When used, decouple V_{REFAC} with a 0.01 μF capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V_{REFAC} output should be left open.

The device is housed in a small 3x3 mm 16 pin QFN package.

The NB6L611 is a member of the ECLinPS MAX[™] family of high performance clock and data management products.

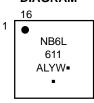
Features

- Input Clock Frequency > 4.0 GHz
- 280 ps Typical Propagation Delay
- 100 ps Typical Rise and Fall Times
- 0.5 ps maximum RMS Clock Jitter
- Differential LVPECL Outputs, 780 mV Amplitude, typical
- LVPECL Operating Range: $V_{CC} = 2.375 \text{ V}$ to 3.63 V with $V_{EE} = 0 \text{ V}$
- NECL Operating Range: $V_{CC} = 0 \text{ V}$ with $V_{EE} = -2.375 \text{ V}$ to -3.63 V
- Internal Input Termination Resistors, 50 Ω
- V_{REFAC} Reference Output Voltage
- Functionally Compatible with Existing 2.5 V / 3.3 V LVEL, LVEP, EP, and SG Devices
- -40°C to +85°C Ambient Operating Temperature
- These are Pb–Free Devices

MARKING DIAGRAM*



QFN-16 MN SUFFIX CASE 485G



A = Assembly Location

L = Wafer Lot Y = Year W = Work Week = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

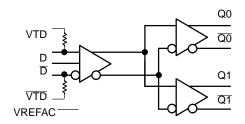


Figure 1. Simplified Logic Diagram

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 9 of this data sheet.

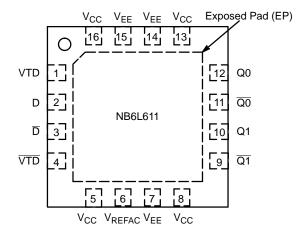


Figure 2. Pin Configuration (Top View)

Table 1. PIN DESCRIPTION

Pin	Name	I/O	Description
1	VTD	-	Internal 50 Ω Termination Pin for D input.
2	D	ECL, CML, LVCMOS, LVDS, LVTTL Input	Noninverted Differential Input. Note1. Internal 50 Ω Resistor to Termination Pin, VTD.
3	D	ECL, CML, LVCMOS, LVDS, LVTTL Input	Inverted Differential Input. Note 1. Internal 50 Ω Resistor to Termination Pin, $\overline{\text{VTD}}$.
4	VTD	-	Internal 50 Ω Termination Pin for $\overline{\mathbf{D}}$ input.
5	V _{CC}	-	Positive Supply Voltage
6	V _{REFAC}		Output Reference Voltage for direct or capacitor coupled inputs
7	V _{EE}	-	Negative Supply Voltage
8	V _{CC}	-	Positive Supply Voltage
9	Q1	LVPECL Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} – 2.0 V.
10	Q1	LVPECL Output	Noninverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} – 2.0 V.
11	Q0	LVPECL Output	Inverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} – 2.0 V.
12	Q0	LVPECL Output	Noninverted Differential Output. Typically Terminated with 50 Ω Resistor to V _{CC} – 2.0 V.
13	V _{CC}	-	Positive Supply Voltage
14	V _{EE}	-	Negative Supply Voltage
15	V _{EE}	-	Negative Supply Voltage
16	V _{CC}	-	Positive Supply Voltage
-	EP	-	The Exposed Pad (EP) on the QFN–16 package bottom is thermally connected to the die for improved heat transfer out of package. The exposed pad must be attached to a heat–sinking conduit. The pad is not electrically connected to the die, but is recommended to be electrically and thermally connected to V_{EE} on the PC board.

In the differential configuration when the input termination pins (VTD, VTD) are connected to a common termination voltage or left open, and if no signal is applied on D/D input, then, the device will be susceptible to self–oscillation.

2. All V_{CC} and V_{EE} pins must be externally connected to a power supply for proper operation.

Table 2. ATTRIBUTES

Cha	Value	
ESD Protection	Human Body Model Machine Model	> 2 kV > 200V
Moisture Sensitivity	16-QFN	Level 1
Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in
Transistor Count		
Meets or exceeds JEDEC S		

For additional information, see Application Note AND8003/D.

Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	Positive Power Supply	V _{EE} = 0 V		4.0	V
V _{EE}	Negative Power Supply	V _{CC} = 0 V		-4.0	V
V _{IO}	Positive Input/Output Voltage Negative Input/Output Voltage	V _{EE} = 0 V V _{CC} = 0 V	$-0.5 \le V_{IO} \le V_{CC} + 0.5 + 0.5 \ge V_{IO} \ge V_{EE} - 0.5$	4.5 -4.5	V V
V _{INPP}	Differential Input Voltage D - D			V_{CC} - V_{EE}	V
I _{IN}	Input Current Through R_T (50 Ω Resistor)	Static Surge		45 80	mA mA
Гоит	Output Current (LVPECL Output)	Continuous Surge		50 100	mA mA
I _{VREFAC}	V _{REFAC} Sink/Source Current			±2.0	mA
T _A	Operating Temperature Range	16 QFN		-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction–to–Ambient) (Note 3)	0 lfpm 500 lfpm	QFN-16 QFN-16	42 35	°C/W °C/W
θЈС	Thermal Resistance (Junction-to-Case)	(Note 3)	QFN-16	4	°C/W
T _{sol}	Wave Solder Pb-Free			265	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

3. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

Table 4. DC CHARACTERISTICS, Multi-Level Inputs V_{CC} = 2.375 V to 3.63 V, V_{EE} = 0 V, or V_{CC} = 0 V, V_{EE} = -2.375 V to 3.63 V, V_{CC} = 0 $-3.63 \text{ V}, T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C}$

Symbol	Characteristic	Min	Тур	Max	Unit		
POWER S	POWER SUPPLY CURRENT						
I _{CC}	Power Supply Current (Inputs and Outputs Open)	30	45	60	mA		
LVPECL C	DUTPUTS (Notes 4 and 5)						
V _{OH}	Output HIGH Voltage $ \begin{array}{c} V_{CC} = 3.3 \; V \\ V_{CC} = 2.5 \; V \end{array} $	V _{CC} – 1075 2225 1425	V _{CC} – 950 2350 1550	V _{CC} – 825 2475 1675	mV		
V _{OL}	Output LOW Voltage $ \begin{array}{c} V_{CC} = 3.3V \\ V_{CC} = 2.5V \end{array} $	V _{CC} – 1875 1475 675	V _{CC} – 1725 1575 775	V _{CC} – 1625 1675 875	mV		
DIFFEREN	ITIAL INPUT DRIVEN SINGLE-ENDED (see Figures 9 and 10) (Note 6	5)					
V _{th}	Input Threshold Reference Voltage Range (Note 7)	V _{EE} + 1050		V _{CC} – 150	mV		
V _{IH}	Single-ended Input HIGH Voltage	V _{th} + 150		V _{CC}	mV		
V _{IL}	Single-ended Input LOW Voltage	V_{EE}		V _{th} – 150	mV		
V _{ISE}	Single-ended Input Voltage Amplitude (V _{IH} - V _{IL})	300		$V_{CC}-V_{EE}$	mV		
V _{REFAC}							
V _{REFAC}	Output Reference Voltage (V _{CC} ≥ 25 V)	V _{CC} – 1.525	V _{CC} – 1.425	V _{CC} – 1.325	mV		
DIFFEREN	ITIAL INPUTS DRIVEN DIFFERENTIALLY (see Figures 11, 12 and 13)	(Note 8)					
V_{IHD}	Differential Input HIGH Voltage	V _{EE} + 1200		V _{CC}	mV		
V_{ILD}	Differential Input LOW Voltage	V _{EE}		V _{CC} – 150	mV		
V_{ID}	Differential Input Voltage (V _{IHD} – V _{ILD})	V _{EE} + 150		$V_{CC}-V_{EE}$	mV		
V_{CMR}	Input Common Mode Range (Differential Configuration) (Note9)	V _{EE} + 950		V _{CC} – 75	mV		
I _{IH}	Input HIGH Current D/D, (VTD/VTD Open)	-150		150	μΑ		
I _{IL}	Input LOW Current D/D, (VTD/VTD Open)	-150		150	μΑ		
TERMINA	TERMINATION RESISTORS						
R _{TIN}	Internal Input Termination Resistor (Measured from D to VTD)	40	50	60	Ω		

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

- LVPECL outputs loaded with 50 Ω to V_{CC} 2.0 V for proper operation.
 Input and output parameters vary 1:1 with V_{CC}.
 V_{th}, V_{IH}, V_{IL}, and V_{ISE} parameters must be complied with simultaneously.
 V_{th} is applied to the complementary input when operating in single–ended mode.
 V_{IHD}, V_{ILD}, V_{ID} and V_{CMR} parameters must be complied with simultaneously.
 V_{CMR} minimum varies 1:1 with V_{EE}, V_{CMR} maximum varies 1:1 with V_{CC}. The V_{CMR} range is referenced to the most positive side of the differential input signal. differential input signal.

Table 5. AC CHARACTERISTICS $V_{CC} = 2.375 \text{ V}$ to 3.63 V, $V_{EE} = 0 \text{ V}$, or $V_{CC} = 0 \text{ V}$, $V_{EE} = -2.375 \text{ V}$ to -3.63 V, $V_{EE} = -2.375 \text{ V}$ to -3.63 V. $T_A = -40^{\circ}C$ to +85°C; (Note 10)

Symbol	Characteristic			Тур	Max	Unit
V _{OUTPP}	Output Voltage Amplitude (@ V _{INPP}) (Note 14) (See Figure 3)	$\begin{aligned} f_{\text{in}} &\leq 1.5 \text{ GHz} \\ f_{\text{in}} &= 2.0 \text{ GHz} \\ f_{\text{in}} &= 3.0 \text{ GHz} \\ f_{\text{in}} &= 4.0 \text{ GHz} \end{aligned}$	725 520 320 170	780 680 500 400		mV
t _{PD}	Propagation Delay	D to Q	225	280	375	ps
t _{SKEW}	Duty Cycle Skew (Note 11) Within Device Skew Device to Device Skew (Note 12)			3	15 15 80	ps
t _{DC}	Output Clock Duty Cycle (Reference Duty Cycle = 50%)	f _{in} ≤ 4.0 GHz	40	50	60	ps
t _{JITTER}	RMS Random Clock Jitter (Note 13)	f _{in} ≤ 4.0 GHz		0.2	0.5	ps
V _{INPP}	Input Voltage Swing/Sensitivity (Differential Configuration) (Note 14)		150		V _{CC} – V _{EE}	mV
t _r ,t _f	Output Rise/Fall Times @ 0.5 GHz (20% – 80%)	Q, \overline{Q}		100	170	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm.

^{14.} Input and output voltage swing is a single-ended measurement operating in differential mode.

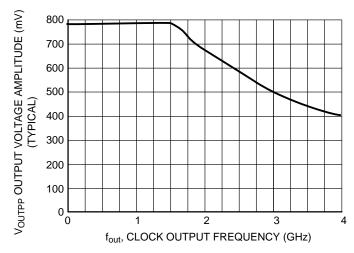


Figure 3. Output Voltage Amplitude (VOUTPP) versus Output Frequency at Ambient Temperature (Typical)

^{10.} Measured by forcing V_{INPP} (MIN) from a 50% duty cycle clock source. All loading with an external R_L = 50 Ω to V_{CC} – 2.0 V. Input edge rates 40 ps (20% - 80%).

^{11.} Duty cycle skew is measured between differential outputs using the deviations of the sum of T_{pw}- and T_{pw}+ @ 0.5GHz. 12. Device to device skew is measured between outputs under identical transition @ 0.5 GHz.

^{13.} Additive RMS jitter with 50% duty cycle clock signal.

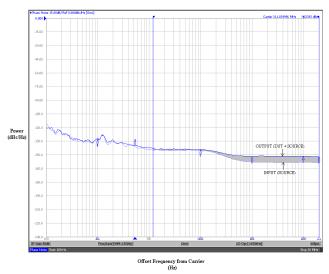


Figure 4. Typical Phase Noise Plot at f_{carrier} = 311.04 MHz

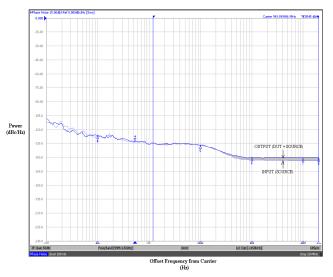


Figure 6. Typical Phase Noise Plot at $f_{carrier} = 1 \text{ GHz}$

The above phase noise plots captured using Agilent E5052A show additive phase noise of the NB6L611 device at frequencies 311.04 MHz, 622.08 MHz, 1 GHz and 2 GHz respectively at an operating voltage of 3.3 V in room temperature. The RMS Phase Jitter contributed by the

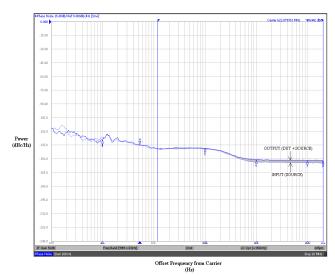


Figure 5. Typical Phase Noise Plot at $f_{carrier} = 622.08 \text{ MHz}$

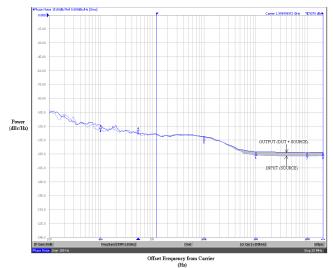


Figure 7. Typical Phase Noise Plot at f_{carrier} = 2 GHz

device (integrated between 12 kHz and 20 MHz; as shown in the shaded region of the plot) at each of the frequencies is 44 fs, 11 fs, 8 fs and 6 fs respectively. The input source used for the phase noise measurements is Agilent E8663B.

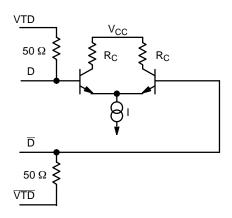


Figure 8. Input Structure

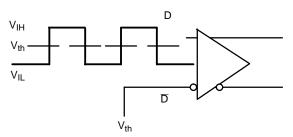


Figure 9. Differential Input Driven Single-Ended

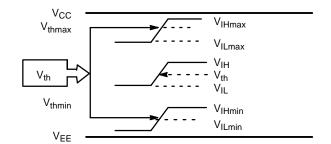


Figure 10. V_{th} Diagram

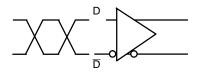


Figure 11. Differential Inputs Driven Differentially

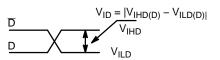


Figure 12. Differential Inputs Driven Differentially

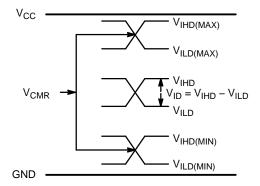


Figure 13. V_{CMR} Diagram

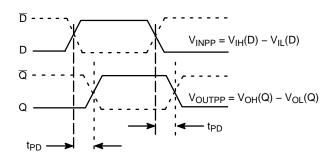


Figure 14. AC Reference Measurement

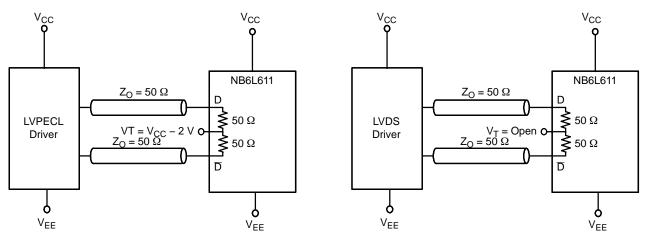


Figure 15. LVPECL Interface

Figure 16. LVDS Interface

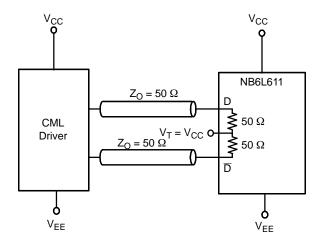
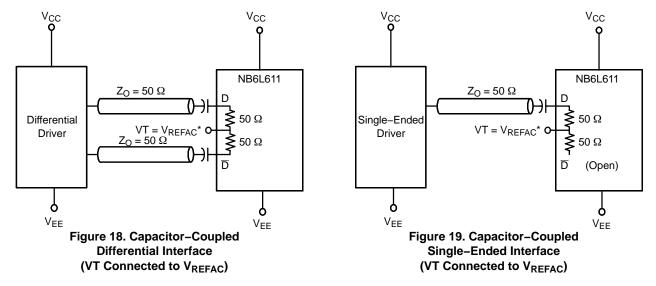


Figure 17. Standard 50 Ω Load CML Interface



 $^{^*}V_{\mbox{\scriptsize REFAC}}$ bypassed to ground with a 0.01 $\mu\mbox{\scriptsize F}$ capacitor

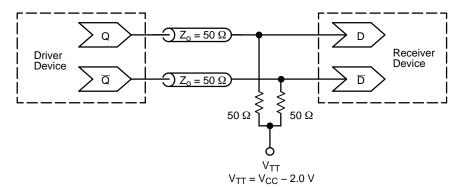


Figure 20. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Shipping [†]
NB6L611MNG	QFN-16 (Pb-free)	123 Units / Rail
NB6L611MNR2G	QFN-16 (Pb-free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.



SCALE 2:1

PIN ONE

LOCATION

2X 0.10 C

2X 0.10 C

// 0.05 C

□ 0.05 C

NOTE 4

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS



回

TOP VIEW

DETAIL B

LEA

В

SEATING PLANE

E

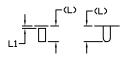
DATE 08 OCT 2021

NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION 6 APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS.
 THE TERMINALS.



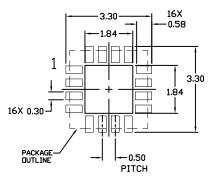
DETAIL B
ALTERNATE
CONSTRUCTIONS



DETAIL A
ALTERNATE TERMINAL
CONSTRUCTIONS

	MILLIME		
DIM	MIN.	N□M.	MAX.
Α	0.80	0.90	1.00
A1	0.00	0.03	0.05
A3		0.20 REF	
b	0.18	0.24	0.30
D	3.00 BSC		
DS	1.65	1.75	1.85
Ε		3.00 BSC	;
E2	1.65	1.75	1.85
e	0.50 BSC		
k	0.18 TYP		
L	0.30	0.40	0.50
L1	0.00	0.08	0.15
L		0.40	0.50

MOUNTING FOOTPRINT



DETAIL A - 16X L
(D) (D) (A) (B) (P) (A) (B) (B) (B) (B) (B) (B) (B) (B) (B) (B
F
0.10[AB]
NDTE 3
e/2
B□TT□M VIEW

SIDE VIEW

GENERIC MARKING DIAGRAM*



XXXXX = Specific Device Code A = Assembly Location

L = Wafer Lot
Y = Year
W = Work Week
Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	QFN16 3X3, 0.5P		PAGE 1 OF 1	

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